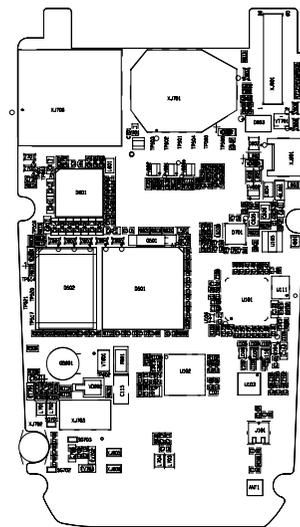


PCB coding	g4rA	layer	top layer	SCALE	1:2	DROWN		CHECKED		SHEET 1 OF 5
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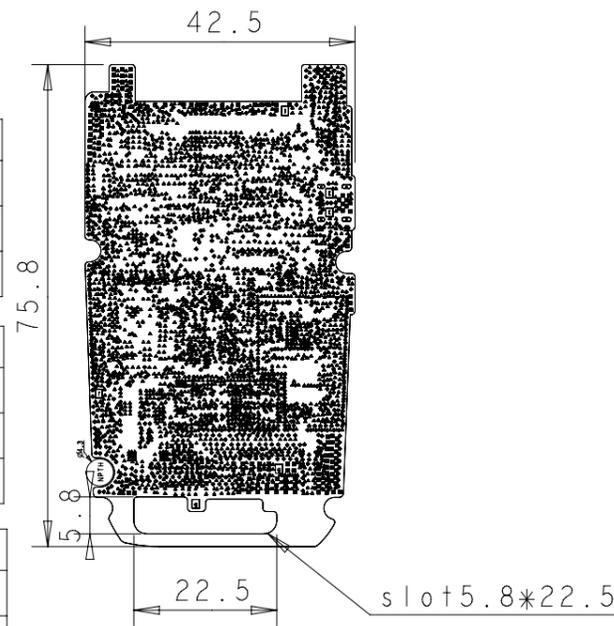
PCB coding	g4rA	layer	top overlay	SCALE	1:2	DROWN		CHECKED		SHEET 2 OF 5
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DRILL CHART: TOP to LAYER2			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
•	0.1016	PLATED	1956

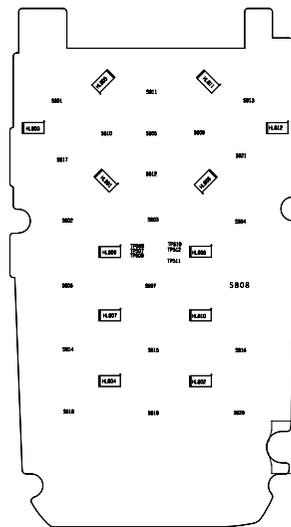
DRILL CHART: LAYER2 to LAYER7			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
•	0.203	PLATED	1141

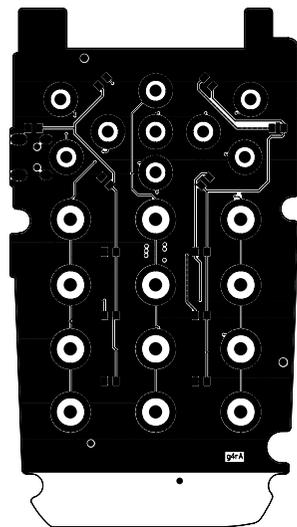
DRILL CHART: LAYER7 to BOTTOM			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
•	0.1016	PLATED	1398

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
•	0.203	PLATED	174
□	1.0	NON-PLATED	2
□	1.0	NON-PLATED	2
□	1.2	NON-PLATED	2
⊙	1.1x0.6	PLATED	2
⊙	1.4x0.6	PLATED	2



MANUFACTURE DETAIL					
Board Thickness(mm)	1.0	According to the layers build-up	Thickness Tolerance	Below ±10%	
Board Material	FR-4		Distorted Degree	Below 0.01mm/mm	
Copper Thickness	X	According to the layers build-up	Silkscreen	Insulative Ink Color:White	
Available Finishes	X	OSP-ENIG	Soldmask	Liquid Sensitive Film	
		ELECTROLESS NICKEL/IMERSION GOLD	Require	X	Green Black Gloss
		Electrolytic Nickel&Gold	Inspection	IPC-A-600E	
		Hot Air Levelling	Standard	IPC-6012B	
Drill Note	Holes Size are after plating		Packet Require:	10PCS IN ONE PACKAGE	
Other Notes For The Pcb During Manufacture			BUILD UP OF LAYERS	According To The Layermark	
1 Fill the vias(drill size=0.5mm) with green oil			Layer Build-up		
2 Mark the manufacturer's logo on the unit			(The copper thickness is after finished)		
3 All the material must comply with RoHS6					
4 Impedance control:		none			
		According to the attached file			
	X	(Microstrip line) Traces with width of 0.11 mm on the TOP layer should be controlled with a 75 Ohm impedance. Ref layer3	LAYER 1	0.065mm Fr4	0.012mm copper
		Traces with width of 0.24 mm on the TOP layer should be controlled with a 50 Ohm impedance. Ref layer3	LAYER 2	0.065mm Fr4	0.012mm copper
		(strip line) Traces with width of 0.12 mm on the layer should be controlled with a 50 Ohm impedance. Ref layer3 & layer5	LAYER 3	0.170mm core	0.018mm copper
		LAYER 4	0.150m Fr-4	0.018mm copper	
			LAYER 5	0.170mm core	0.018mm copper
			LAYER 6	0.065mm Fr-4	0.018mm copper
			LAYER 7	0.065mm Fr-4	0.012mm copper
			LAYER 8	0.065mm Fr-4	0.012mm copper
5 PCB must withstand at least 4 cycles of the lead-free soldering reflow process that specified on the profile of 260°C peak-temperature and 10 seconds duration-time,without any delamination, bubble, and physical or chemical reaction which will affect PCB reliability happened.			TOTAL THICKNESS=1.0mm		





PCB coding	g4rA	layer	bottom layer	SCALE	1:2	DROWN		CHECKED		SHEET 5 OF 5
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